



#### 30V P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C	
	11mΩ @ V <sub>GS</sub> = -10V	-13A	
-30V	17mΩ @ V <sub>GS</sub> = -4.5V	-9.9A	

- Low On-Resistance
- Low Gate Threshold Voltage

**Features and Benefits** 

- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- **PPAP Capable (Note 4)**

## **Description**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

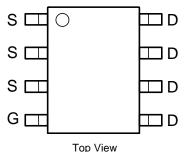
#### **Mechanical Data**

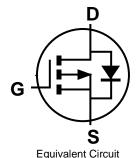
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074g (Approximate)





Top View





Ordering Information (Note 5)

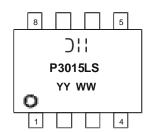
Part Number	Case	Packaging
DMP3015LSSQ-13	SO-8	2500/Tape & Reel

Internal Schematic

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q10x and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



☐ H= Manufacturer's Marking P3015LS = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 18 = 2018)WW = Week (01 - 53)

DMP3015LSSQ Document number: DS38013 Rev. 3 - 2



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V <sub>DSS</sub>	-30	V	
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Drain Current (Note 6)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	ID	-13 -9.75	А
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	-45	Α

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	$P_{D}$	2.5	W
Thermal Resistance, Junction to Ambient	$R_{\Theta JA}$	50	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- 6. Device mounted on 2 oz. Copper pads on FR-4 PCB with  $R_{\Theta JA} = +50^{\circ}$ C/W.
- 7. Pulse width ≤10µS, Duty Cycle ≤1%.

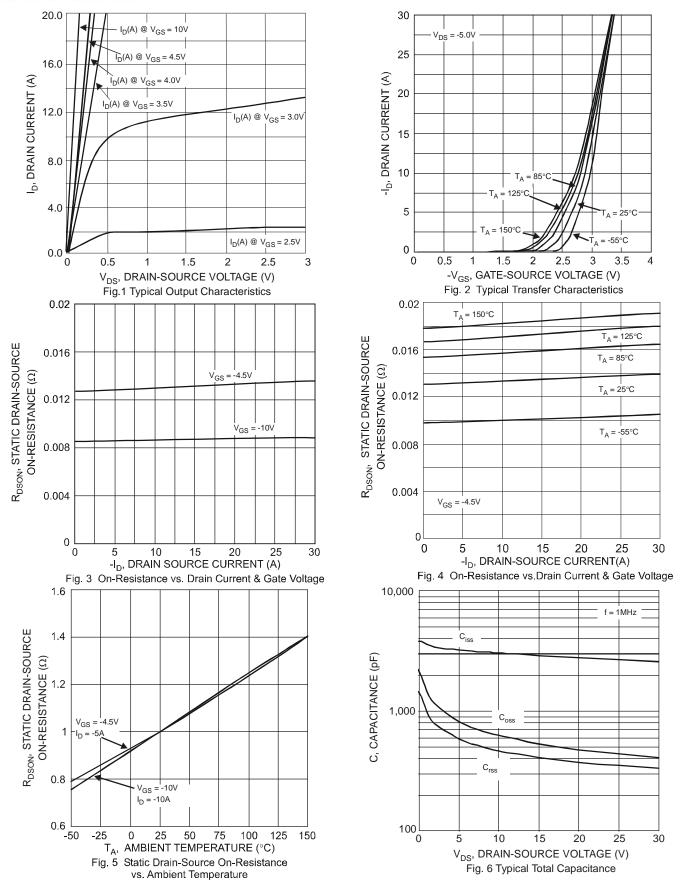
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	-	-1	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(th)}$	-1	1	-2	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	D-s/s/iii	_	9	11	mΩ	$V_{GS} = -10V, I_D = -13A$
Static Diani-Source On-Resistance	R <sub>DS(ON)</sub>	_	14	17	11152	$V_{GS} = -4.5V, I_D = -10A$
Forward Transconductance	9fs	_	15		S	$V_{DS} = -15V, I_{D} = -8A$
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	-0.5	1	-1.1	V	$V_{GS} = 0V, I_{S} = -2.1A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C <sub>iss</sub>	_	2,748	l	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	Coss	_	357		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	356	l	pF	1 = 1.0101112
Gate Resistance	$R_{G}$	_	2.0		Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ f = 1.0MHz
SWITCHING CHARACTERISTICS (Note 9)						
Total Gate Charge	Qg	_	30.0	-	nC	$V_{DS} = -10V$ , $V_{GS} = -4.5V$ , $I_{D} = -13A$
Total Gate Charge		_	60.4	-		$V_{DS} = -10V$ , $V_{GS} = -10V$ , $I_{D} = -13A$
Gate-Source Charge	$Q_{gs}$	_	7.2	l	110	$V_{DS} = -10V$ , $V_{GS} = -10V$ , $I_{D} = -13A$
Gate-Drain Charge	$Q_{gd}$	_	16.4			$V_{DS} = -10V$ , $V_{GS} = -10V$ , $I_{D} = -13A$
Turn-On Delay Time	t <sub>d(on)</sub>	_	11.2	_		
Rise Time	t <sub>r</sub>	_	12.4	_	nS	$V_{DS} = -15V, V_{GS} = -10V,$
Turn-Off Delay Time	t <sub>d(off)</sub>	_	104.9		113	$I_D = -1A, R_G = 6.0\Omega$
Fall Time	t <sub>f</sub>	_	61.7	1		

Notes:

- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.







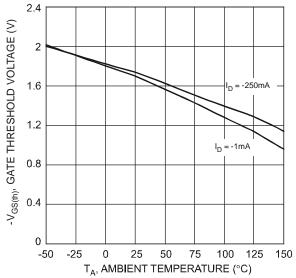
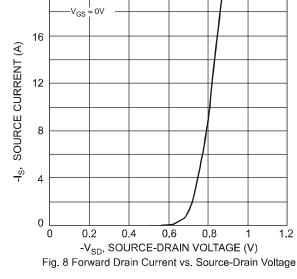
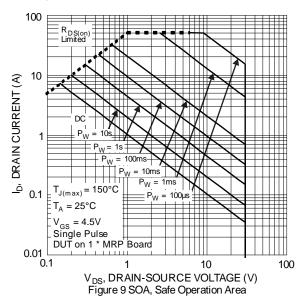


Fig. 7 Gate Threshold Variation vs. Ambient Temperature



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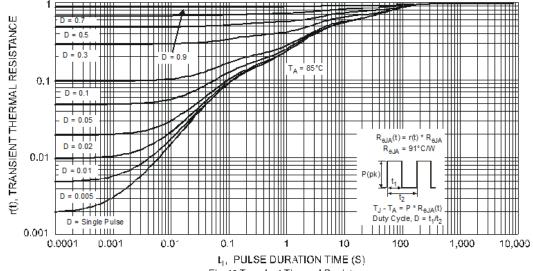
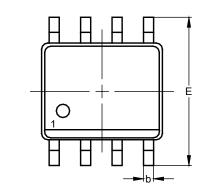


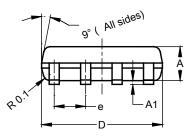
Fig. 10 Transient Thermal Resistance

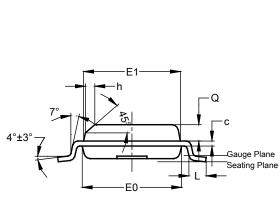


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.







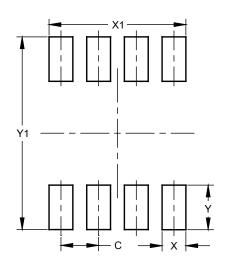
SO-8

SO-8

SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
b	0.30	0.50	0.40		
C	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е	_	-	1.27		
h	_		0.35		
L	0.62	0.82	0.72		
Q	0.60	0.70	0.65		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	1.27			
Х	0.802			
X1	4.612			
Υ	1.505			
Y1	6.50			



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